



# Product Change Notification

**Change Notification #:** 117530 - 00  
**Change Title:** Intel® Server Heatsink FXXWK1UHSB,  
Intel® Server Heatsink FXXWK1UHSE,  
Intel® Server System S9232WK1HAC,  
PCN 117530-00, Product Material,  
Added e-clip on Heatsink  
**Date of Publication:** March 31, 2020

## Key Characteristics of the Change:

Product Material

## Forecasted Key Milestones:

<b>Date Customer Must be Ready to Receive Post-Conversion Material: *</b>	April 16, 2020
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\* Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.

## Description of Change to the Customer:

Intel is adding an “e-clip” to the heatsinks included in the Intel products listed in the Products Affected table. The “e-clip” is shown in figure 2. e-clip heatsink.

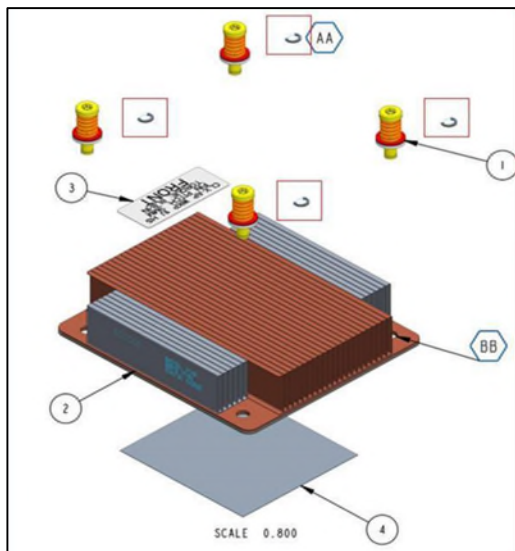


Figure 1. heatsink before change

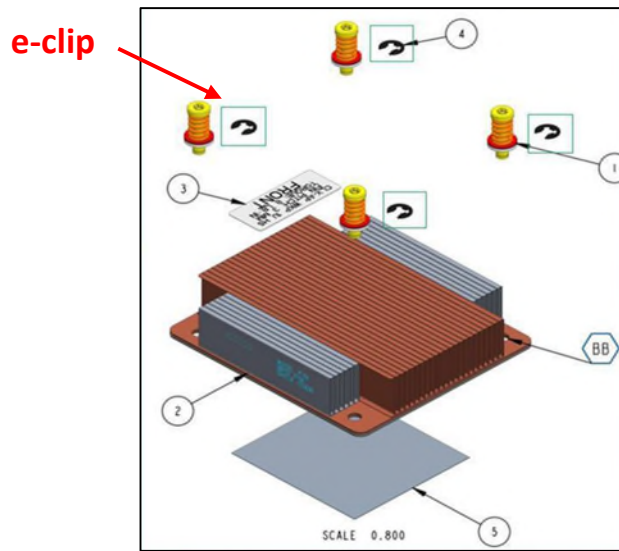


Figure 2. heatsink with “e-clip”

## Customer Impact of Change and Recommended Action:

Intel does not expect any other impact to customers from these changes described but encourages customers to understand the change and determine the impact on their applications.

## Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change TA	Post Change TA
S9232WK1HAC	999MVJ	K58931-002	K58931-003
FXXWK1UHSF	999MVL	K81788-001	K81788-002
FXXWK1UHSB	999MVM	K81789-001	K81789-002

## PCN Revision History:

**Date of Revision:**

March 31, 2020

**Revision Number:**

00

**Reason:**

Originally Published PCN



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**Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.**

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